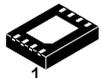


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

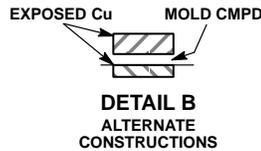
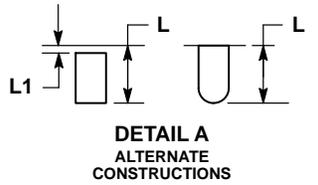
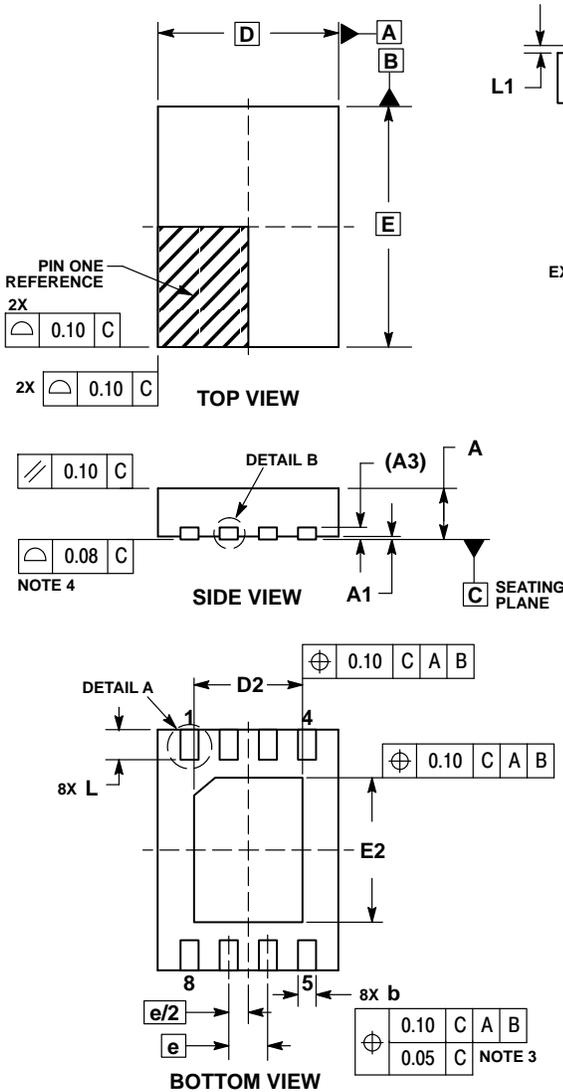
ON Semiconductor®



SCALE 2:1

WDFN8 3x4, 0.65P
CASE 509AF
ISSUE C

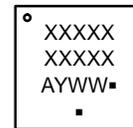
DATE 06 MAY 2014



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM THE TERMINAL TIP.
 4. PROFILE TOLERANCE APPLIES TO THE EXPOSED PAD AS WELL AS THE LEADS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.80
A1	0.00	0.05
A3	0.20	REF
b	0.20	0.30
D	3.00	BSC
D2	1.70	1.90
E	4.00	BSC
E2	2.30	2.50
e	0.65	BSC
L	0.45	0.55
L1	---	0.10

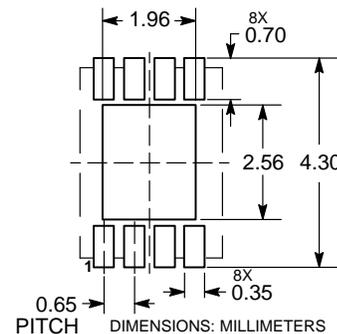
GENERIC MARKING DIAGRAM*



- A = Assembly Location
 - Y = Year
 - WW = Work Week
 - = Pb-Free Package
- (Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NEW STANDARD:		
DESCRIPTION:	WDFN8 3X4, 0.65P	PAGE 1 OF 2

